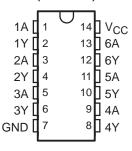
- Controlled Baseline
  - One Assembly/Test Site, One Fabrication Site
- Extended Temperature Performance of -55°C to 125°C
- Enhanced Diminishing Manufacturing Sources (DMS) Support
- Enhanced Product-Change Notification
- Qualification Pedigree<sup>†</sup>
- EPIC™ (Enhanced-Performance Implanted CMOS) Process
- Operating Range 2-V to 5.5-V V<sub>CC</sub>
- ESD Protection Exceeds 1500 V Per MIL-STD-833, Method 3015; Exceeds 150 V Using Machine Model (C = 200 pF, R = 0)

† Component qualification in accordance with JEDEC and industry standards to ensure reliable operation over an extended temperature range. This includes, but is not limited to, Highly Accelerated Stress Test (HAST) or biased 85/85, temperature cycle, autoclave or unbiased HAST, electromigration, bond intermetallic life, and mold compound life. Such qualification testing should not be viewed as justifying use of this component beyond specified performance and environmental limits.

#### D OR PW PACKAGE (TOP VIEW)



#### description/ordering information

The SN74AHC04 contains six independent inverters. This device performs the Boolean function  $Y = \overline{A}$ .

#### **ORDERING INFORMATION**

TA	PACKA	\GE <sup>‡</sup>	ORDERABLE PART NUMBER	TOP-SIDE MARKING
5500 1- 40500	SOIC - D	Tape and reel	SN74AHC04MDREP	AHC04MEP
–55°C to 125°C	TSSOP – PW	Tape and reel	SN74AHC04MPWREP	AHC04EP

<sup>‡</sup> Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

## FUNCTION TABLE (each inverter)

INPUT A	OUTPUT Y
Н	L
L	Н

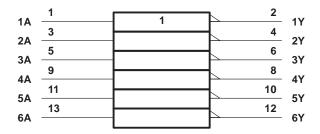


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#### logic symbol<sup>†</sup>



<sup>&</sup>lt;sup>†</sup> This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

#### logic diagram, each inverter (positive logic)



#### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, V <sub>CC</sub>	0.5 V to 7 V
Input voltage range, V <sub>I</sub> (see Note 1)	0.5 V to 7 V
Output voltage range, V <sub>O</sub> (see Note 1)	0.5 V to V <sub>CC</sub> + 0.5 V
Input clamp current, $I_{ K }(V_1 < 0)$	–20 mA
Output clamp current, I <sub>OK</sub> (V <sub>O</sub> < 0 or V <sub>O</sub> > V <sub>CC</sub> )	±20 mA
Continuous output current, $I_O(V_O = 0 \text{ to } V_{CC})$	±25 mA
Continuous current through V <sub>CC</sub> or GND	±50 mA
Package thermal impedance, θ <sub>JA</sub> (see Note 2): D package	86°C/W
PW package	113°C/W
Storage temperature range, T <sub>stq</sub>	–65°C to 150°C

<sup>‡</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
  - 2. The package thermal impedance is calculated in accordance with JESD 51-7.



### recommended operating conditions (see Note 3)

			MIN	MAX	UNIT
Vcc	Supply voltage		2	5.5	V
		V <sub>CC</sub> = 2 V	1.5		
$V_{IH}$	High-level input voltage	V <sub>CC</sub> = 3 V	2.1		V
	High-level input voltage  Low-level input voltage  Input voltage  Output voltage  High-level output current  Low-level output current  Input transition rise or fall rate	V <sub>CC</sub> = 5.5 V	3.85		
		V <sub>CC</sub> = 2 V		0.5	
$V_{IL}$	Low-level input voltage	V <sub>CC</sub> = 3 V		V	
		V <sub>CC</sub> = 5.5 V		1.65	
$V_{I}$	Input voltage		0	5.5	V
VO	Output voltage		0	VCC	V
		V <sub>CC</sub> = 2 V		-50	μΑ
loh	High-level output current	$V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$		-4	A
	/IL Low-level input voltage  /I Input voltage  /O Output voltage  OH High-level output current  OL Low-level output current  Δt/Δv Input transition rise or fall rate	$V_{CC} = 5 V \pm 0.5 V$		-8	mA
		V <sub>CC</sub> = 2 V		50	μΑ
lOL	Low-level output current	$V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$		4	A
	High-level input voltage  Low-level input voltage  Input voltage  Output voltage  High-level output current  Low-level output current  Input transition rise or fall rate	$V_{CC} = 5 V \pm 0.5 V$		8	mA
41/4	Leave to the self-self-self-self-self-self-self-self-	$V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$		100	0./
ΔΨΔΨ	input transition rise of fall rate	$V_{CC} = 5 V \pm 0.5 V$		20	ns/V
TA	Operating free-air temperature		-55	125	°C

NOTE 3: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

## electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

24244555	TEGT CONDITIONS	.,	T,	չ = 25°C	;		MAV	
PARAMETER	TEST CONDITIONS	VCC	MIN	TYP	MAX	MIN	MAX	UNIT
		2 V	1.9	2		1.9		
Voн	$I_{OH} = -50 \mu\text{A}$	3 V	2.9	3		2.9		
		4.5 V	4.4	4.5		4.4		V
	$I_{OH} = -4 \text{ mA}$	3 V	2.58			2.48		
	$I_{OH} = -8 \text{ mA}$	4.5 V	3.94			3.8		
		2 V			0.1		0.1	V
	I <sub>OL</sub> = 50 μA	3 V			0.1		0.1	
V <sub>OL</sub>		4.5 V			0.1		0.1	
	I <sub>OL</sub> = 4 mA	3 V			0.36		0.5	
	I <sub>OL</sub> = 8 mA	4.5 V			0.36		0.5	
lį	$V_I = 5.5 \text{ V or GND}$	0 V to 5.5 V			±0.1		±1	μΑ
lcc	$V_I = V_{CC}$ or GND, $I_O = 0$	5.5 V			2		20	μΑ
Ci	$V_I = V_{CC}$ or GND	5 V		2	10		·	pF

# switching characteristics over recommended operating free-air temperature range, $V_{CC}$ = 3.3 V $\pm$ 0.3 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	TO (OUTPUT)	LOAD	T,	λ = 25°C	;		MAX	UNIT
	(INPUT)		CAPACITANCE	MIN	TYP	MAX	MIN		
<sup>t</sup> PLH		V	C <sub>L</sub> = 15 pF		5	8.9	1	10.5	
t <sub>PHL</sub>	А	Υ			5	8.9	1	10.5	ns
<sup>t</sup> PLH	^	V	O: 50 = 5		7.5	11.4	1	13	no
tPHL	A	ſ	C <sub>L</sub> = 50 pF		7.5	11.4	1	13	ns

# switching characteristics over recommended operating free-air temperature range, $V_{CC}$ = 5 V $\pm$ 0.5 V (unless otherwise noted) (see Figure 1)

DADAMETED	FROM	то	LOAD	T,	չ = 25°C	;	BAINI	BAAV	LINUT
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MIN	MAX	UNIT
<sup>t</sup> PLH		V	C <sub>L</sub> = 15 pF		3.8	5.5	1	6.5	
<sup>t</sup> PHL	А	Y			3.8	5.5	1	6.5	ns
<sup>t</sup> PLH	۸	V	C: - 50 pF		5.3	7.5	1	8.5	20
<sup>t</sup> PHL	T A CL	C <sub>L</sub> = 50 pF	_	5.3	7.5	1	8.5	ns	

## noise characteristics, $V_{CC} = 5 \text{ V}$ , $C_L = 50 \text{ pF}$ , $T_A = 25^{\circ}\text{C}$ (see Note 4)

	PARAMETER	MIN	TYP	MAX	UNIT
V <sub>OL(P)</sub>	Quiet output, maximum dynamic V <sub>OL</sub>		0.4		V
V <sub>OL(V)</sub>	Quiet output, minimum dynamic V <sub>OL</sub>		-0.4		V
V <sub>OH(V)</sub>	Quiet output, minimum dynamic VOH		4.8		V
VIH(D)	High-level dynamic input voltage	3.5			V
V <sub>IL(D)</sub>	Low-level dynamic input voltage			1.5	V

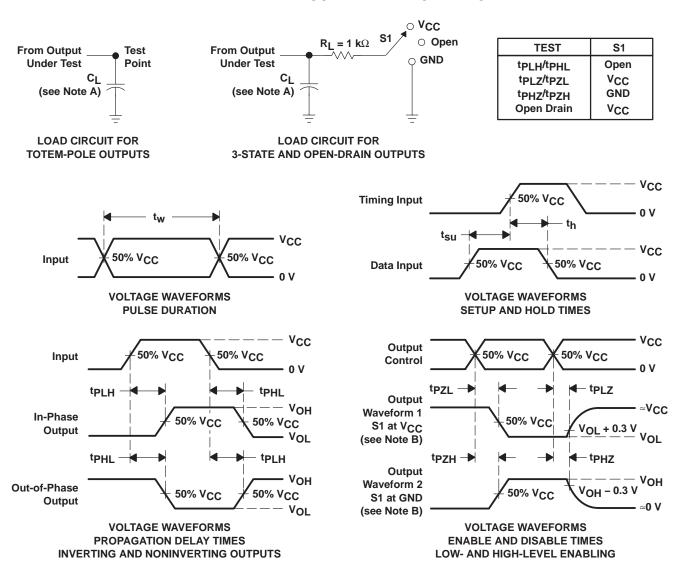
NOTE 4: Characteristics are for surface-mount packages only.



### operating characteristics, $V_{CC} = 5 \text{ V}$ , $T_A = 25^{\circ}\text{C}$

PARAMETER	TEST CONDITIONS	TYP	UNIT
C <sub>pd</sub> Power dissipation capacitance	No load, f = 1 MHz	12	pF

#### PARAMETER MEASUREMENT INFORMATION



NOTES: A. C<sub>L</sub> includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  1 MHz,  $Z_O = 50 \Omega$ ,  $t_f \leq 3$  ns,  $t_f \leq 3$  ns.
- D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms



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#### PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
							(6)				
SN74AHC04MDREP	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	AHC04MEP	Samples
SN74AHC04MPWREP	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	AHC04EP	Samples
V62/03646-01XE	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	AHC04EP	Samples
V62/03646-01YE	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	AHC04MEP	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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### **PACKAGE OPTION ADDENDUM**

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#### OTHER QUALIFIED VERSIONS OF SN74AHC04-EP:

Catalog: SN74AHC04

Automotive: SN74AHC04-Q1

Military: SN54AHC04

NOTE: Qualified Version Definitions:

• Catalog - TI's standard catalog product

Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects

• Military - QML certified for Military and Defense Applications

## **PACKAGE MATERIALS INFORMATION**

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#### TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

#### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74AHC04MDREP	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74AHC04MPWREP	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

## **PACKAGE MATERIALS INFORMATION**

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#### \*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74AHC04MDREP	SOIC	D	14	2500	340.5	336.1	32.0
SN74AHC04MPWREP	TSSOP	PW	14	2000	356.0	356.0	35.0

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